

AMENDMENTS TO THE CLAIMS

IN THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application. Please amend the claims as follows.

Please cancel claims 1-14 and 17-19.

1-14. (canceled).

15. (currently amended) A method comprising:

heating a first element comprising an initial dimension, where the first element is part of an assembly, to a first temperature sufficient to expand the initial dimension to a first dimension, the first dimension greater than the initial dimension; and

removing the first element from the assembly

wherein the first element can only be removed from the assembly when the first element is at the first temperature, and wherein heating the first element from the assembly is a means of de-encrypting the assembly.

16. (original) The method of claim 15, wherein a coefficient of thermal expansion of the first element comprises a first value and a coefficient of thermal expansion of the assembly comprises a second value, the first value different than the second value.

17-19. (canceled).

20. (previously presented) The method of claim 15, wherein the first element has a thermal expansion coefficient of between approximately 10 micrometers per degree Celsius per meter and approximately 25 micrometers per degree Celsius per meter.

21. (previously presented) The method of claim 15, wherein the first element is fashioned from aluminum.

22. (previously presented) The method of claim 21, wherein the first element further comprises a polymer.

23. (previously presented) The method of claim 22, wherein the polymer has a coefficient of thermal expansion between approximately 0 micrometers per degree Celsius per meter and approximately 1000 micrometers per degree Celsius per meter.

24. (canceled).

25. (previously presented) The method of claim 16, wherein the first element can only be removed from the assembly when the first element is at the first temperature.

26. (canceled).

27. (previously presented) The method of claim 25, wherein heating the first element from the assembly is a means of de-encrypting the assembly.

28. (currently amended) The method of claim 1526, wherein a particular manner, location or sequence of heating is used to remove the first element.

29. (previously presented) The method of claim 27, wherein a particular manner, location or sequence of heating is used to remove the first element.

30. (previously presented) The method of claim 28, wherein prior to heating in the particular manner, location or sequence, it is not apparent that the first element can be removed.

31. (previously presented) The method of claim 29, wherein prior to heating in the particular manner, location or sequence, it is not apparent that the first element can be removed.

32. (currently amended) The method of claim 15, wherein a means of heating the first element is ~~selected from~~ one or more members selected from the group consisting of a hot liquid, a heating torch, an induction heating oven, a radiator, a heating pad, and a remote heating device.

33. (currently amended) The method of claim 16, wherein a means of heating the first element is ~~selected from~~ one or more members selected from the group consisting of a hot liquid, a heating torch, an induction heating oven, a radiator, a heating pad, and a remote heating device.

34. (previously presented) The method of claim 15 wherein the means of heating the first element is a hot liquid.

35. (canceled).

36. (canceled).

37. (canceled).

38. (previously presented) The method of claim 15, further comprising
a preliminary step of heating the first element and adding the first element which
is heated to a second element so as to create the assembly.

39. (previously presented) The method of claim 38, wherein said heating the first
element is from a first temperature to a third temperature.